

1 2 3 4 5 6 7 8

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F

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C

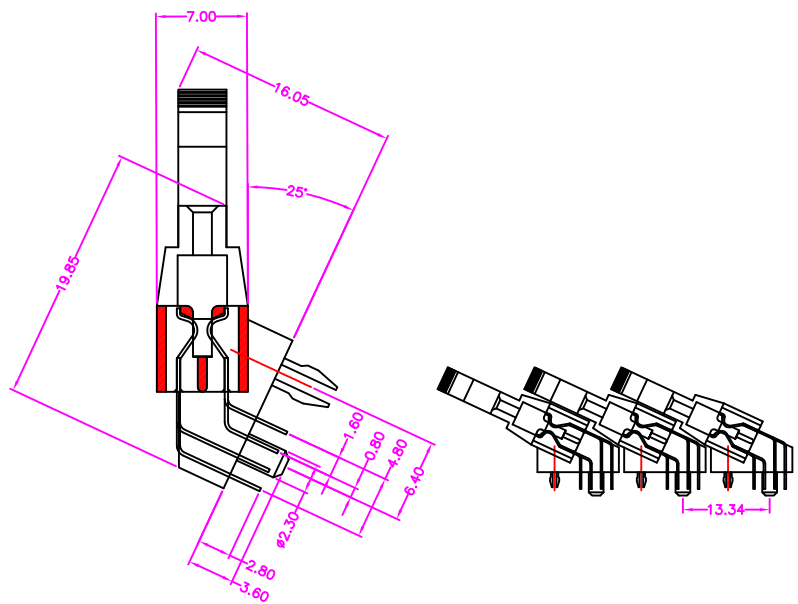
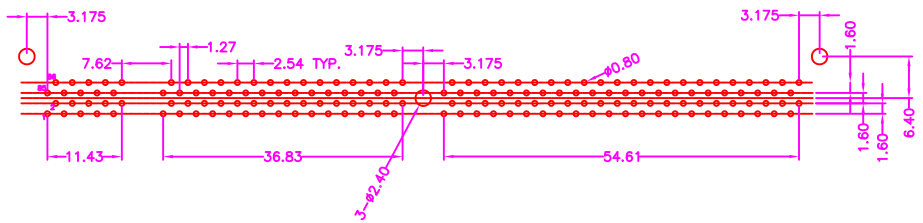
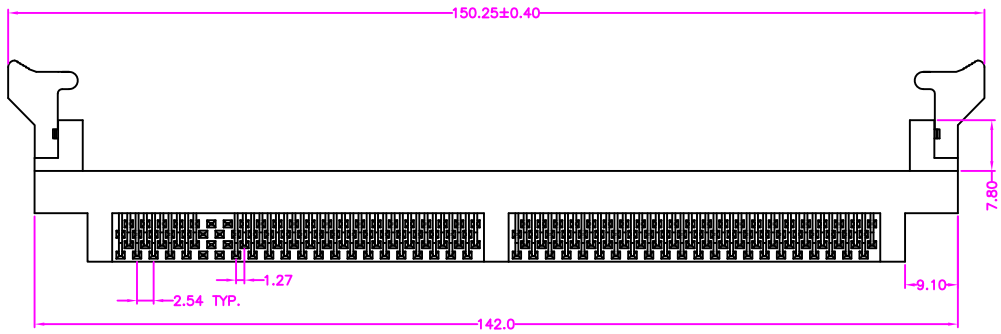
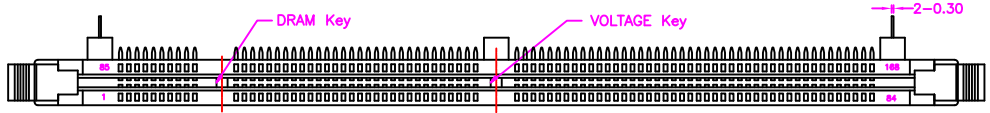
C

B

B

A

A



MATERIALS

HOUSING: HI-TEMP. PLASTIC (UL 94V-0)
 LATCH: THERMOPLASTIC (UL 94V-0)
 BOARDLOCK: COPPER ALLOY, TIN PLATING
 TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA
 TIN PLATING ON SOLDER TAIL

SPECIFICATION

CURRENT RATING: 1 AMP MAX
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
 CONTACT RESISTANCE: 30m OHMS MAX
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
 OPERATION TEMPERATURE: -40°C~+85°C

PART NUMBER:
4MSAD - 1 6 8 * T - 1 2 0

SERIES _____ NO. OF POS. _____ TRAY PACKAGE _____
 TIN PLATING ON SOLDER TAIL _____

CONTACT PLATED OPTION _____
 1: GOLD FLASH
 3: 3u" GOLD
 5: 5u" GOLD
 6: 10u" GOLD
 7: 15u" GOLD
 9: 30u" GOLD

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TOLERANCES		MEMORY SOCKET SERIES				
X.X ±0.3		TITLE DIMM SOCKET 168 PIN, 1.27mm PITCH, PCB MOUNT				
X.XX ±0.2		25° DEGREE FEMALE, WITH BOARDLOCK				
X.XXX ±0.1		DRAWN BY		CHECKED BY		APPROVED BY
Angle ±5°		<i>Janice</i>		<i>Lion</i>		<i>Benson</i>
UNIT		SCALE	SIZE	DRAW NO.	REV.	Sheet
10033		MM	NONE	A4	4MSAD-001	A 1/1

A	RELEASE	2012.5.18
REV.	DESCRIPTION	DATE

1 2 3 4 5 6 7 8